Intel® Dual Band Wireless-AC 8265

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Specifications

Essentials

Status	Launched
Launch Date	Q1'16
Board Form Factor	M.2 2230 or M.2 1216
Weight (in grams)	2.6
Operating Temperature Range	0°C to 80°C
Supported Operating Systems	Microsoft Windows 7*, Microsoft Windows 8.1*, Microsoft Windows 10*, Linux* (limited feature support), Android
Warranty Period	1 yrs
Antenna	2x2
Product Brief	Link
Conflict Free	Yes

Networking Specifications

TX/RX Streams	2x2
Bands	2.4 GHz, 5 GHz
Max Speed	867 Mbps
Wi-Fi CERTIFIED*	Yes
Compliance	FIPS, FISMA
Integrated Bluetooth	Yes
System Interface Type	PCIe, USB

Package Specifications

Package Size	22mm x 30mm x 2.4mm

Advanced Technologies

Intel® Wireless Display	Yes
4G WiMAX Wireless Technology	No
Supported Under vPro	Yes
Intel® Smart Connect Technology	Yes

Related Products

Intel® Wireless Products

Intel® Wireless 8000 Series

CONFLICT FREE

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PCN/MDDS Information

946657: PCN | MDDS
946658: PCN | MDDS
949399: PCN | MDDS
951075: PCN | MDDS
951076: PCN | MDDS
951820: PCN | MDDS
951821: PCN | MDDS

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

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